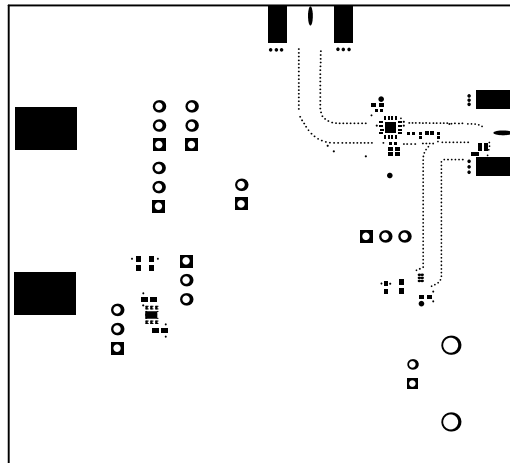
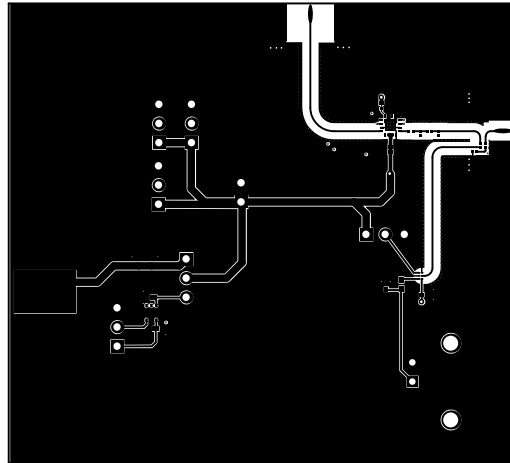


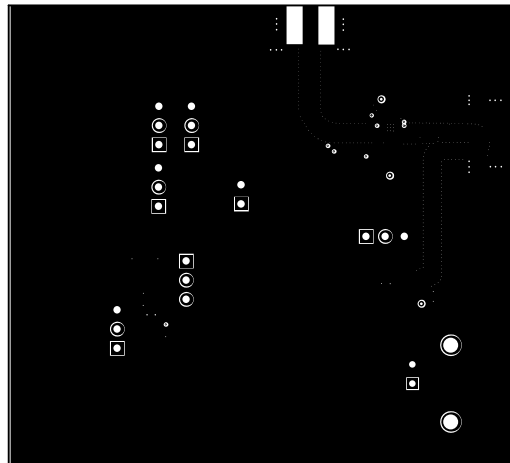
ALL ARTWORK VIEWED FROM TOP SIDE	PROJECT NAME = Wideband RF Power Detector	
LAYER NAME = Top Overlay	ARTWORK # = .prj_BapeBNminorRev	
PLOT NAME = Top Overlay	GENERATED : 12/22/2015 5:54:16 PM	Texas Instruments



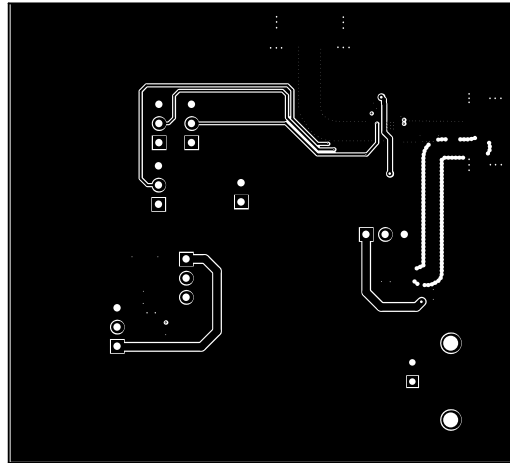
ALL ARTWORK VIEWED FROM TOP SIDE	PROJECT NAME = Wideband RF Power Detector	
LAYER NAME = Top Solder	ARTWORK # = 880.pr j_BapeBNminorRev	
PLOT NAME = Top Solder Mask	GENERATED : 12/22/2015 5:54:17 PM	Texas Instruments



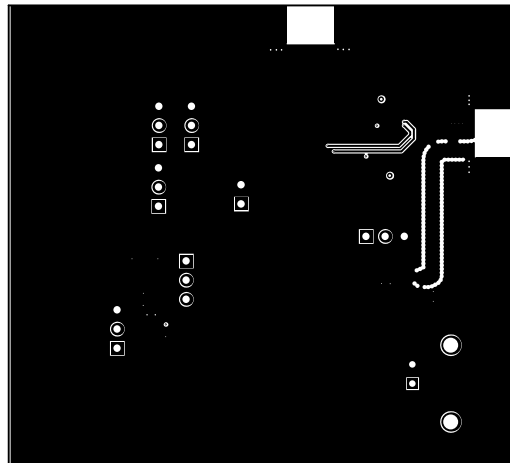
ALL ARTWORK VIEWED FROM TOP SIDE	PROJECT NAME = Wideband RF Power Detector	
LAYER NAME = L1<Top>	ARTWORK # = .prj_BapeBNminorRev	
PLOT NAME = Top Layer	GENERATED : 12/22/2015 5:54:17 PM	Texas Instruments



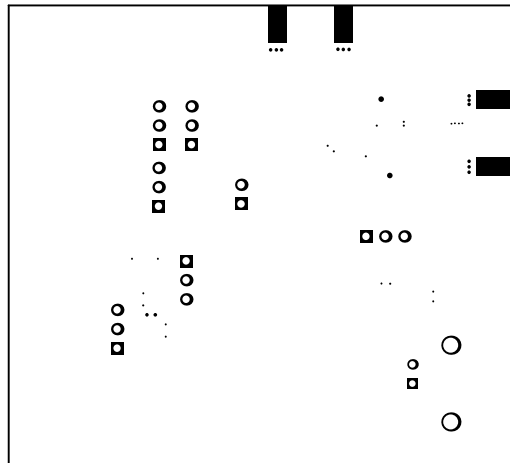
ALL ARTWORK VIEWED FROM TOP SIDE	PROJECT NAME = Wideband RF Power Detector	
LAYER NAME =	ARTWORK # = .prj_BapeBNminorRev	
PLOT NAME = MidLayer1	GENERATED : 12/22/2015 5:54:18 PM	Texas Instruments



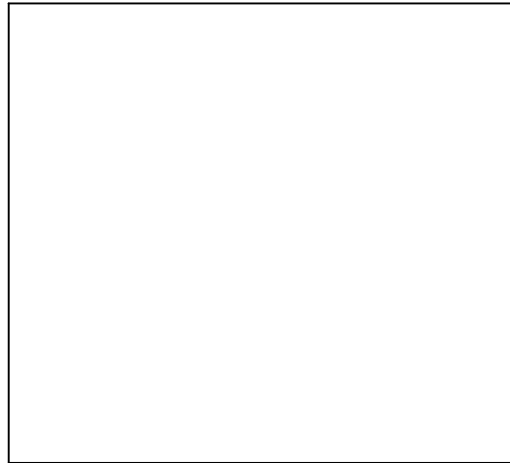
ALL ARTWORK VIEWED FROM TOP SIDE	PROJECT NAME = Wideband RF Power Detector	
LAYER NAME =	ARTWORK # = .prj_BapeBNminorRev	
PLOT NAME = MidLayer2	GENERATED : 12/22/2015 5:54:19 PM	Texas Instruments



ALL ARTWORK VIEWED FROM TOP SIDE	PROJECT NAME = Wideband RF Power Detector	
LAYER NAME = L4(Bottom)	ARTWORK # = .prj_BapeBNminorRev	
PLOT NAME = Bottom Layer	GENERATED : 12/22/2015 5:54:20 PM	Texas Instruments

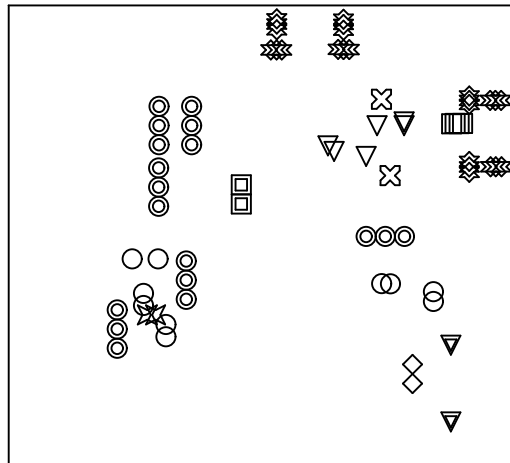


ALL ARTWORK VIEWED FROM TOP SIDE	PROJECT NAME = Wideband RF Power Detector	
LAYER NAME = Bottom Solder	ARTWORK # = 880.prj_BapeBNminorRev	
PLOT NAME = Bottom Solder Mask	GENERATED : 12/22/2015 5:54:20 PM	Texas Instruments



ALL ARTWORK VIEWED FROM TOP SIDE	PROJECT NAME = Wideband RF Power Detector	
LAYER NAME = Bottom Overlay	ARTWORK # = .prj_BapeBNminorRev	
PLOT NAME = Bottom Overlay	GENERATED : 12/22/2015 5:54:21 PM	Texas Instruments

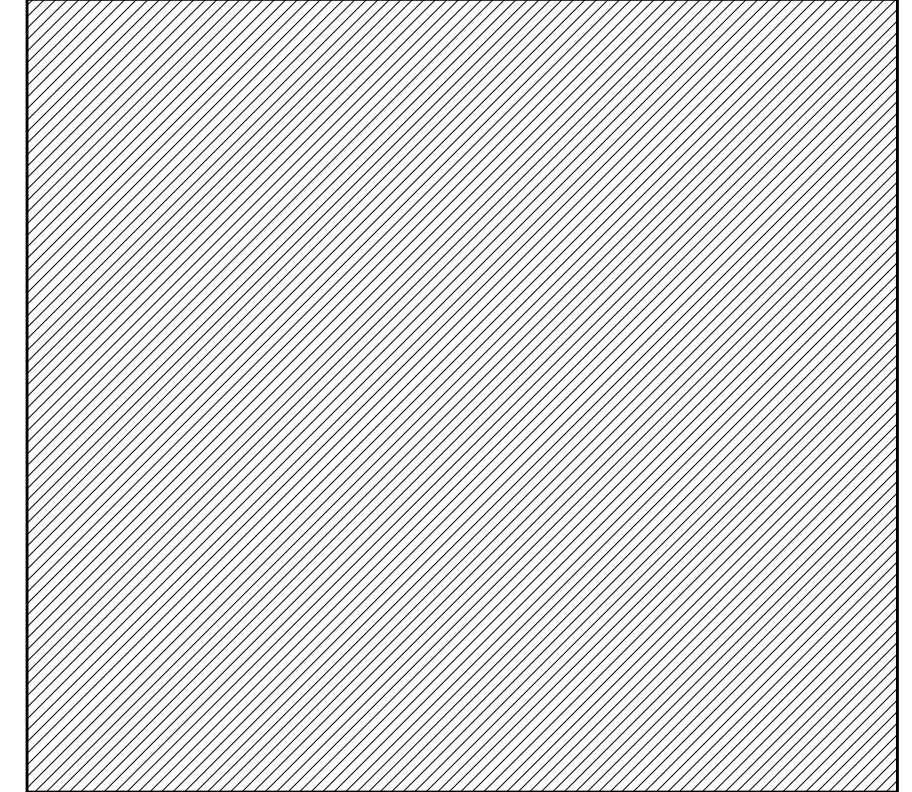




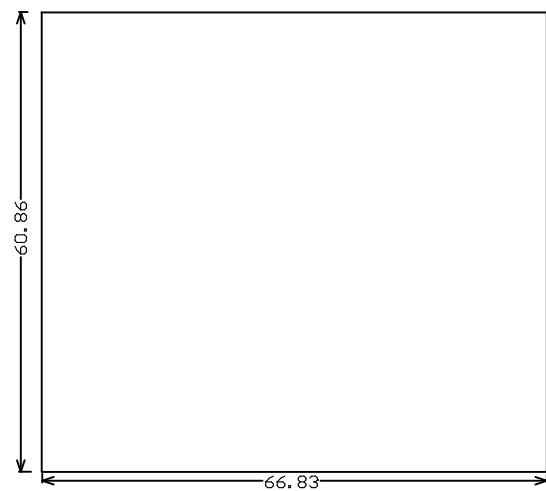
Symbol	Quantity	Finished Hole Size	Plated	Hole Type
□	4	3.94mil (0.100mm)	PTH	Round
○	10	5.91mil (0.150mm)	PTH	Round
▽	6	6.00mil (0.152mm)	PTH	Round
✕	2	7.87mil (0.200mm)	PTH	Round
⊛	24	9.84mil (0.250mm)	PTH	Round
⊞	2	15.00mil (0.381mm)	PTH	Round
◇	2	35.00mil (0.889mm)	PTH	Round
●	18	39.37mil (1.000mm)	PTH	Round
■	2	40.00mil (1.016mm)	PTH	Round
▼	2	79.00mil (2.007mm)	PTH	Round
72 Total				

ALL ARTWORK VIEWED FROM TOP SIDE	PROJECT NAME = Wideband RF Power Detector		
LAYER NAME = Drill Drawing	ARTWORK # = 880.pr j_BapeBNminorRev		
PLOT NAME = Drill Drawing	GENERATED : 12/22/2015 5:54:22 PM	Texas Instruments	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	L1(Top)	Copper	1.65mil		
4	Dielectric1	FR-4	8.00mil	4.8	
5	L2	Copper	1.40mil		
6	Dielectric2	FR-4	32.00mil	4.2	
7	L3	Copper	1.40mil		
8	Dielectric3	FR-4	8.00mil	4.2	
9	L4(Bottom)	Copper	1.65mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



ALL ARTWORK VIEWED FROM TOP SIDE	PROJECT NAME = Wideband RF Power Detector	
LAYER NAME = M12 Stackup	ARTWORK # = 880.pr.j_BapeBNminorRev	
PLOT NAME = Board Layer Stackup	GENERATED : 12/22/2015 5:54:22 PM	Texas Instruments



ALL ARTWORK VIEWED FROM TOP SIDE	PROJECT NAME = Wideband RF Power Detector	
LAYER NAME = M2 Board Dimensions	ARTWORK # = 880.prj_BapeBNminorRev	
PLOT NAME = Board Dimensions	GENERATED : 12/22/2015 5:54:23 PM	Texas Instruments

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